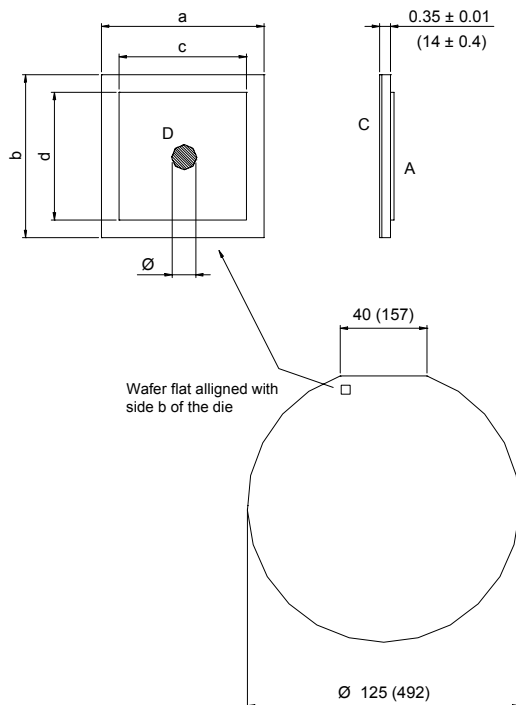


SCHOTTKY DIE 50 x 50 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).

2. CONTROLLING DIMENSION: (MILS).

3. DIMENSIONS AND TOLERANCES:

 $a = 1.27 + 0, - 0.01$ $(50 + 0, - 0.4)$ $b = 1.27 + 0, - 0.01$ $(50 + 0, - 0.4)$ $c = 1.12 + 0, - 0.01$ $(44 + 0, - 0.4)$ $d = 1.12 + 0, - 0.01$ $(44 + 0, - 0.4)$ $\varnothing = 0.7 \pm 0.1$ (30 ± 4)

4. LETTER DESIGNATION:

A = Anode (Top Metal)

C = Cathode (Back Metal)

D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:

Recommended Blade

SEMITEC S1025 QS00 Blade

Sawing Street

 $0.05 + 0, - 0.005$ $(2 + 0, - 0.2)$

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC050 R 015x5x	125	15	n.a. contact factory			
SC050 S 020x5x	150	20	n.a. contact factory			
SC050 S 030x5x	150	30	30	12	0.47 @ 2A	SMB
SC050 S 045x5x	150	45	15	8	0.55 @ 2A	DO-41
SC050 S 060x5x	150	60	20	6	0.60 @ 2A	SMA
SC050 H 045x5x	175	45	n.a. contact factory			
SC050 H 100x5x	175	100	n.a. contact factory			
SC050 H 150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC050xxxx A 5x	Wire Bondable	—	Al 30 kÅ	—	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC050xxxx S 5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC050xxxx B 5	Inked Probed Unsawn Wafer (Wafer in Box)	6300
SC050xxxx R 5	Probed Die in Tape & Reel	n. a.
SC050xxxx P 5	Probed Die in Waffle Pack	6300
SC050xxxx F 5	Inked Probed Sawn Wafer on Film	6300

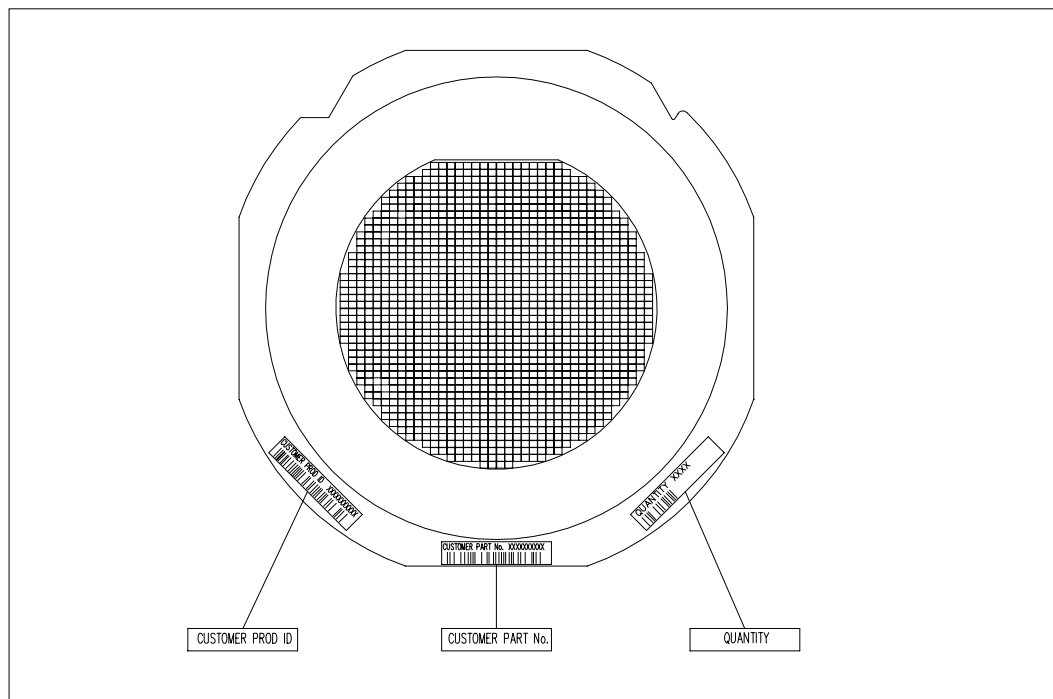
Ordering Information Table

Device Code						
1	2	3	4	5	6	7
SC	050	H	150	A	5	B

1	- Schottky Die
2	- Chip Dimension in Mils
3	- Process (see Electrical Characteristics Table)
4	- Voltage code: Code = V_{RRM}
5	- Chip surface metallization (see Mechanical Data Table)
6	- Wafer Diameter in inches
7	- Packaging (see Packaging Table)

H = 830 Process
R = OR'ing Process
S = Standard Process

Wafer on Film

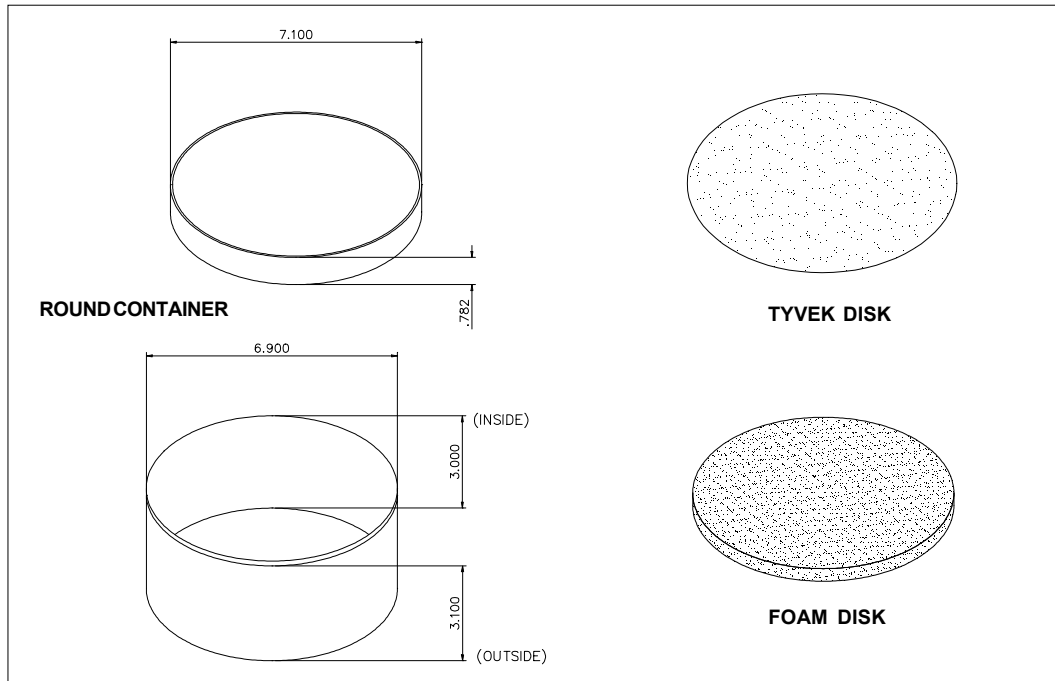


SC050.....5.

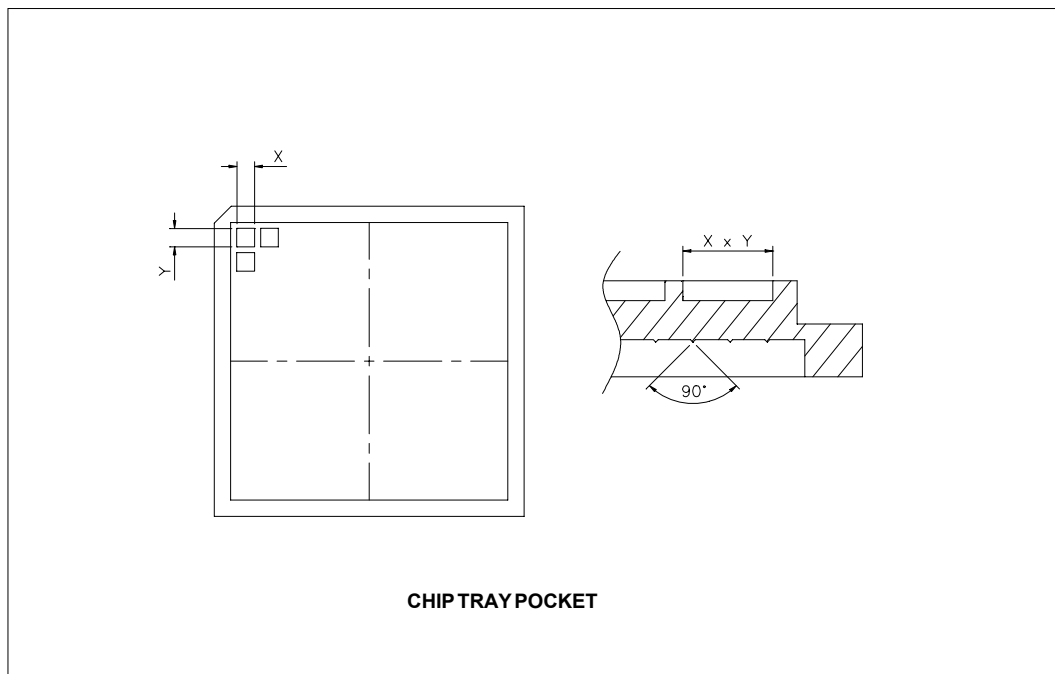
Bulletin I0510J rev. A 05/01

International
IOR Rectifier

Wafer in Box



Die in Waffle Pack



WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 U.S.A. Tel: (310) 322 3331. Fax: (310) 322 3332.
EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, U.K. Tel: ++ 44 1883 732020. Fax: ++ 44 1883 733408.
IR CANADA: 15 Lincoln Court, Brampton, Markham, Ontario L6T3Z2. Tel: (905) 453 2200. Fax: (905) 475 8801.
IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg. Tel: ++ 49 6172 96590. Fax: ++ 49 6172 965933.
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino. Tel: ++ 39 11 4510111. Fax: ++ 39 11 4510220.
IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.
IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994. Tel: ++ 65 838 4630.
IR TAIWAN: 16 Fl. Suite D.207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan. Tel: 886 2 2377 9936.

<http://www.irf.com>

Fax-On-Demand: +44 1883 733420

Data and specifications subject to change without notice.